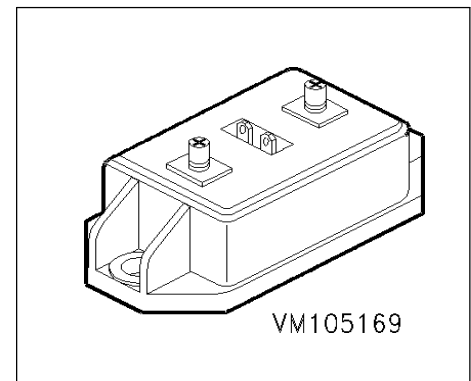


SIMOPAC® MODULE

- Single switch power MOSFET module
- N channel, enhancement mode
- Avalanche rated
- Package with insulated metal base plate
- Built in gate series resistor



| Type | V_{DS} | I_D | $R_{DS(on)max}$ | Package | Ordering Code |
|------------|----------|-------|-----------------|-----------|------------------|
| BSM 181 AR | 800 V | 36 A | 0.24 Ω | SSW MOS 1 | C67076-A1017-A20 |

Maximum Ratings

| Parameter | Symbol | Values | Unit |
|---------------------------------------------------------------|-------------|---------------|------------------|
| Drain source voltage | V_{DS} | 800 | V |
| Drain-gate voltage $R_{GS} = 20 \text{ k}\Omega$ | V_{DGR} | 800 | |
| Gate source voltage | V_{GS} | ± 20 | |
| Continuous drain current $T_C = 25 \text{ }^\circ\text{C}$ | I_D | 36 | A |
| DC drain current, pulsed $T_C = 25 \text{ }^\circ\text{C}$ | I_{Dpuls} | 144 | |
| Power dissipation $T_C = 25 \text{ }^\circ\text{C}$ | P_{tot} | 700 | W |
| Chip temperature | T_{jmax} | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -40 ... + 125 | |

| | | | |
|----------------------------------------------|------------|---------------|-------|
| Thermal resistance chip - case | R_{thJC} | ≤ 0.18 | K/W |
| Thermal resistance case - heat sink | R_{thCA} | ≤ 0.05 | |
| Insulation test voltage, $t = 1 \text{ min}$ | V_{is} | 2.5 | kV ac |
| Creepage distance, drain-source | | 16 | mm |
| Clearance, drain-source | | 11 | |
| DIN humidity category, DIN 40 040 | | F | |
| DIN humidity category, DIN IEC 68-1 | | 40 / 125 / 56 | |

Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|--------|-----------|-------------|---------------|
| | | min. | typ. | max. | |
| Static Characteristics | | | | | |
| Gate threshold voltage $V_{GS} = V_{DS}, I_D = 1 \text{ mA}$ | $V_{GS(th)}$ | 2.1 | 3 | 4 | V |
| Drain-Source on-resistance $V_{GS} = 10 \text{ V}, I_D = 23 \text{ A}$ | $R_{DS(on)}$ | - | 0.18 | 0.24 | Ω |
| Zero gate voltage drain current $V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 25^\circ\text{C}$ $V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}, T_j = 125^\circ\text{C}$ | I_{DSS} | - | 50 300 | 100 1000 | μA |
| Gate-source leakage current $V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$ | I_{GSS} | - | 10 | 100 | nA |

Reverse Diode

| | | | | | |
|--------------------------------------------------------------------------------------------------|----------|------|------|-----|---------------|
| Inverse diode continuous forward current $T_C = 25^\circ\text{C}$ | I_S | - | - | 36 | A |
| Inverse diode direct current, pulsed $T_C = 25^\circ\text{C}$ | I_{SM} | - | - | 144 | |
| Inverse diode forward voltage $V_{GS} = 0 \text{ V}, I_F = 72 \text{ A}$ | V_{SD} | 0.65 | 0.9 | 1.2 | V |
| Reverse recovery time $V_R = 100 \text{ V}, I_F = I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$ | t_{rr} | - | 1200 | - | ns |
| Reverse recovery charge $V_R = 100 \text{ V}, I_F = I_S, di_F/dt = 100 \text{ A}/\mu\text{s}$ | Q_{rr} | - | 42 | - | μC |

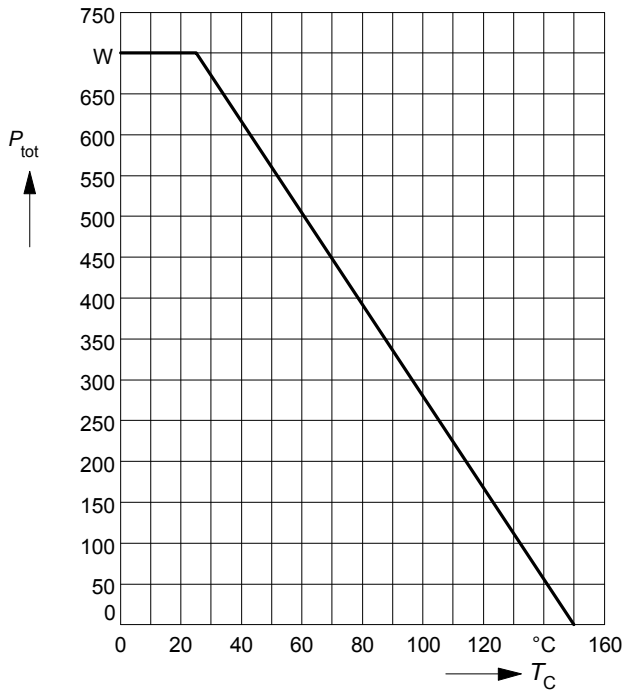
Electrical Characteristics, at $T_j = 25^\circ\text{C}$, unless otherwise specified

| Parameter | Symbol | Values | | | Unit |
|---------------------------------------------------------------------------------------------------------------------------|--------------|--------|------|------|------|
| | | min. | typ. | max. | |
| Dynamic Characteristics | | | | | |
| Transconductance $V_{DS} \geq 2 * I_D * R_{DS(on)max}$, $I_D = 23 \text{ A}$ | g_{fs} | 16 | 33 | - | S |
| Input capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{iss} | - | 10 | 14 | nF |
| Output capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{oss} | - | 1.2 | 1.7 | |
| Reverse transfer capacitance $V_{GS} = 0 \text{ V}$, $V_{DS} = 25 \text{ V}$, $f = 1 \text{ MHz}$ | C_{rss} | - | 0.6 | 0.8 | |
| Turn-on delay time $V_{DD} = 400 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 23 \text{ A}$ $R_{GS} = 3.3 \Omega$ | $t_{d(on)}$ | - | 60 | - | ns |
| Rise time $V_{DD} = 400 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 23 \text{ A}$ $R_{GS} = 3.3 \Omega$ | t_r | - | 30 | - | |
| Turn-off delay time $V_{DD} = 400 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 23 \text{ A}$ $R_{GS} = 3.3 \Omega$ | $t_{d(off)}$ | - | 710 | - | |
| Fall time $V_{DD} = 400 \text{ V}$, $V_{GS} = 10 \text{ V}$, $I_D = 23 \text{ A}$ $R_{GS} = 3.3 \Omega$ | t_f | - | 100 | - | |

Power dissipation

$P_{tot} = f(T_C)$

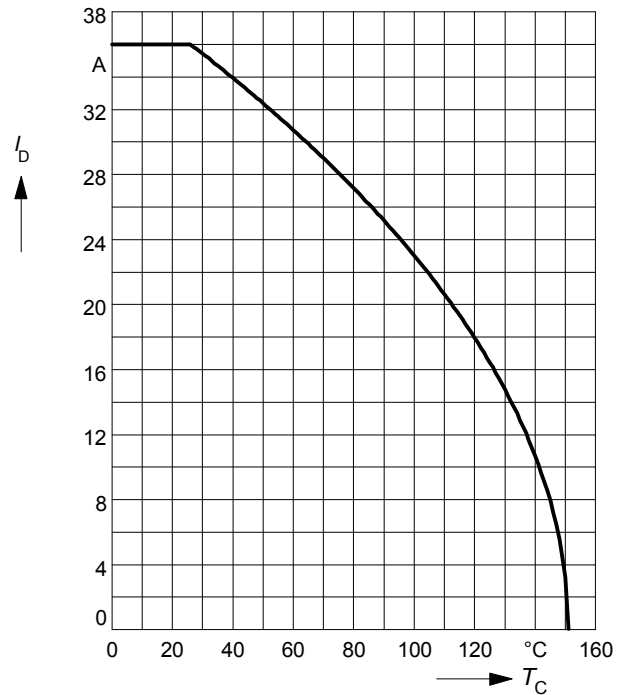
parameter: $T_j \leq 150^\circ\text{C}$



Drain current

$I_D = f(T_C)$

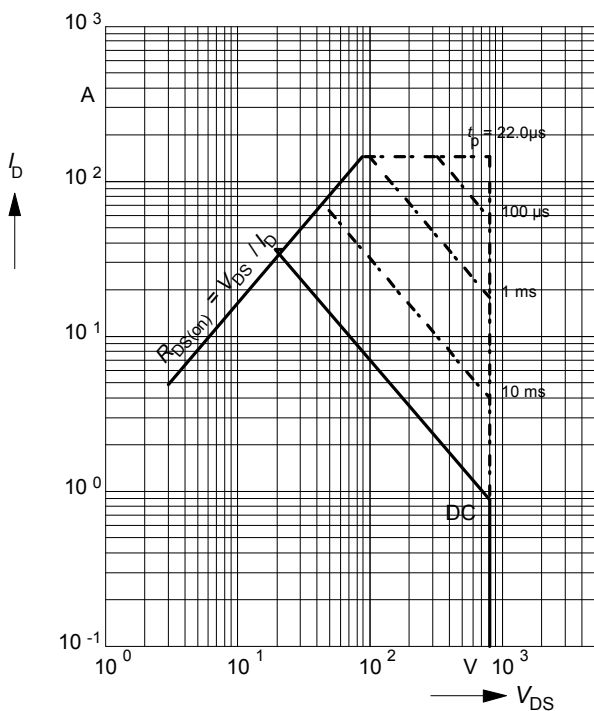
parameter: $V_{GS} \geq 10\text{ V}$, $T_j \leq 150^\circ\text{C}$



Safe operating area

$I_D = f(V_{DS})$

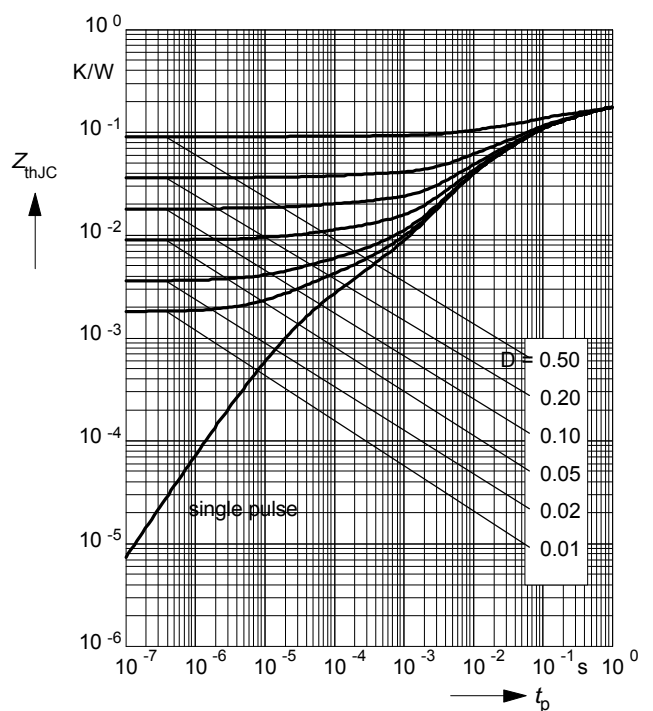
parameter: *single puls*, $T_C = 25^\circ\text{C}$, $T_j \leq 150^\circ\text{C}$



Transient thermal impedance

$Z_{thJC} = f(t_p)$

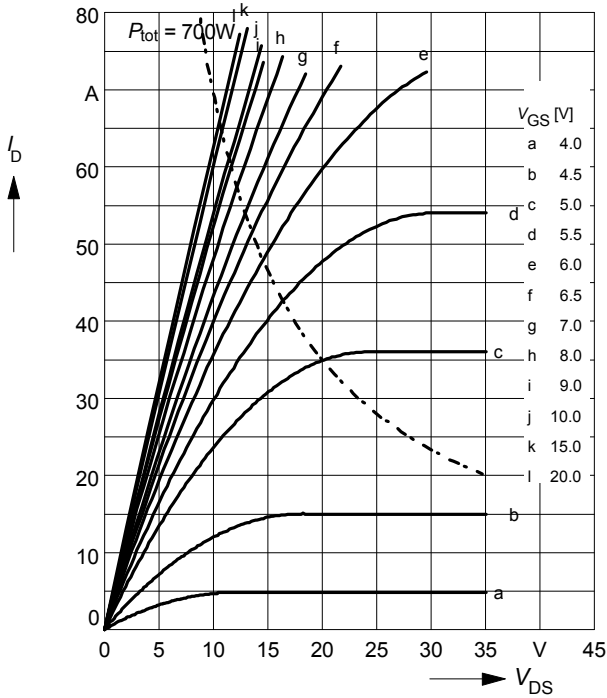
parameter: $D = t_p / T$



Typ. output characteristics

$I_D = f(V_{DS})$

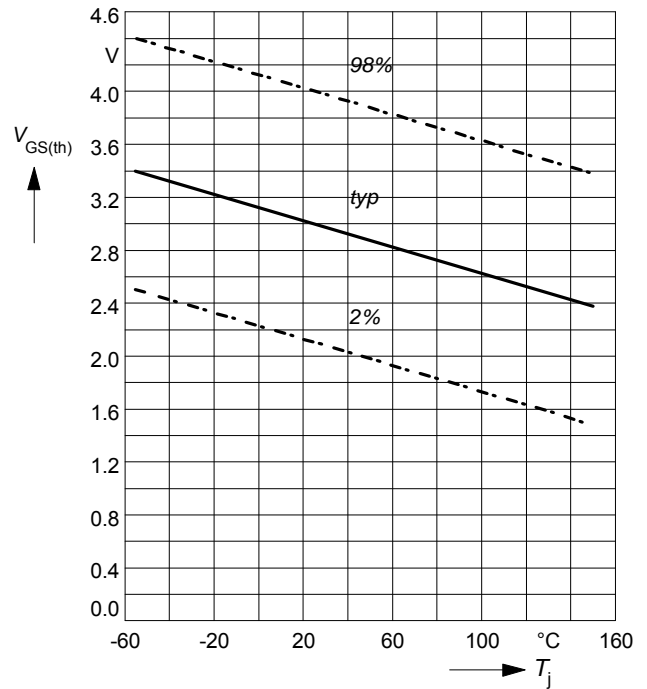
parameter: $t_p = 80 \mu s$, $T_j = 25^\circ C$



Gate threshold voltage

$V_{GS(th)} = f(T_j)$

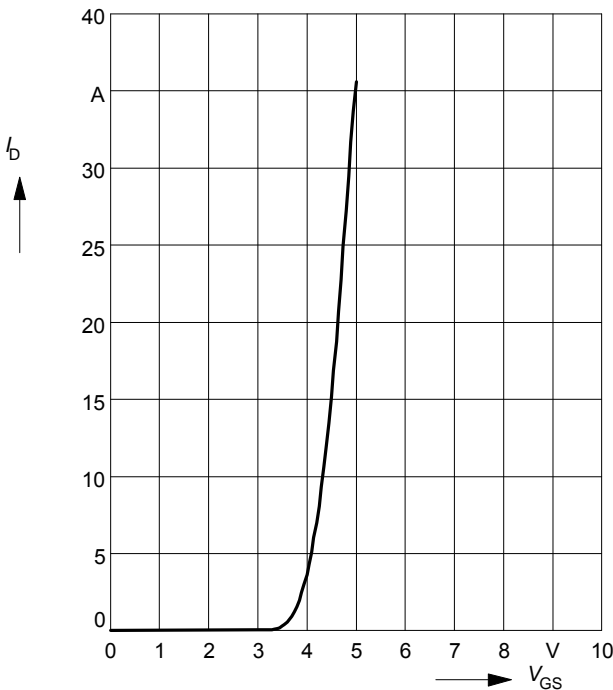
parameter: $V_{GS} = V_{DS}$, $I_D = 1 \text{ mA}$



Typ. transfer characteristic

$I_D = f(V_{GS})$

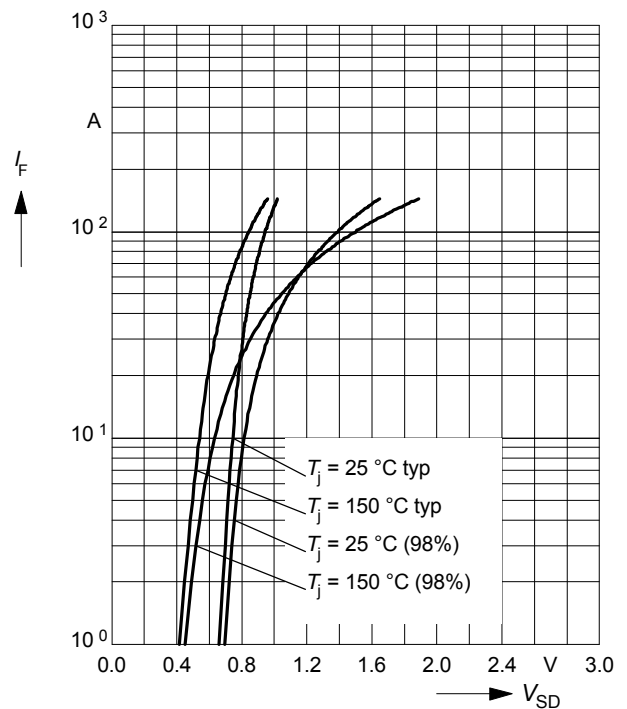
parameter: $t_p = 80 \mu s$, $V_{DS} = 25 \text{ V}$



Forward characteristics of reverse diode

$I_F = f(V_{SD})$

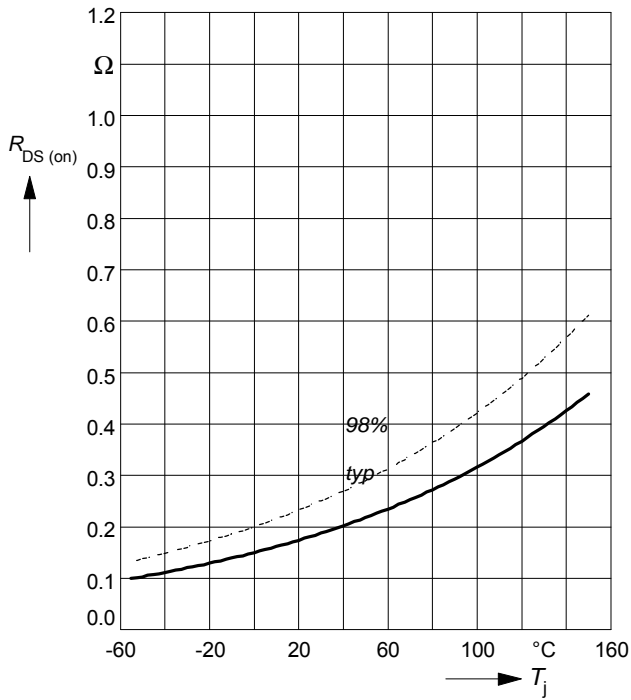
parameter: T_j , $t_p = 80 \mu s$



Drain-source on-resistance

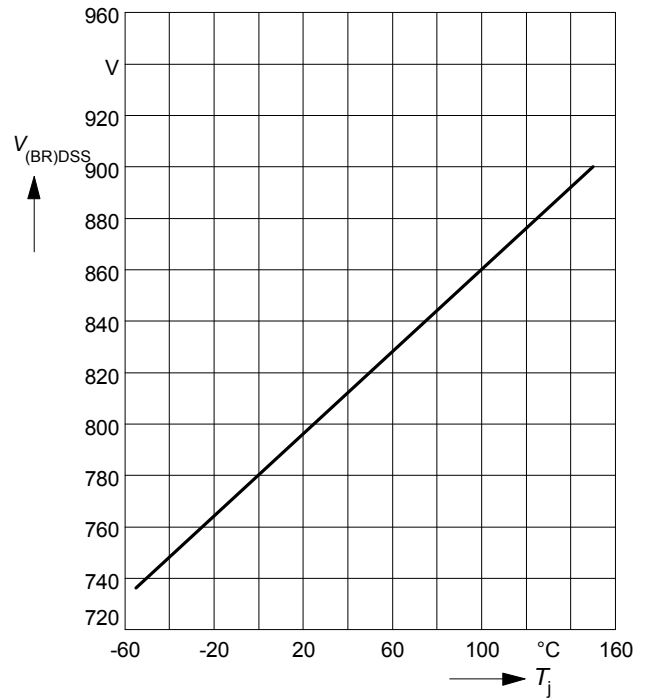
$$R_{DS(on)} = f(T_j)$$

parameter: $I_D = 23\text{ A}$, $V_{GS} = 10\text{ V}$



Drain-source breakdown voltage

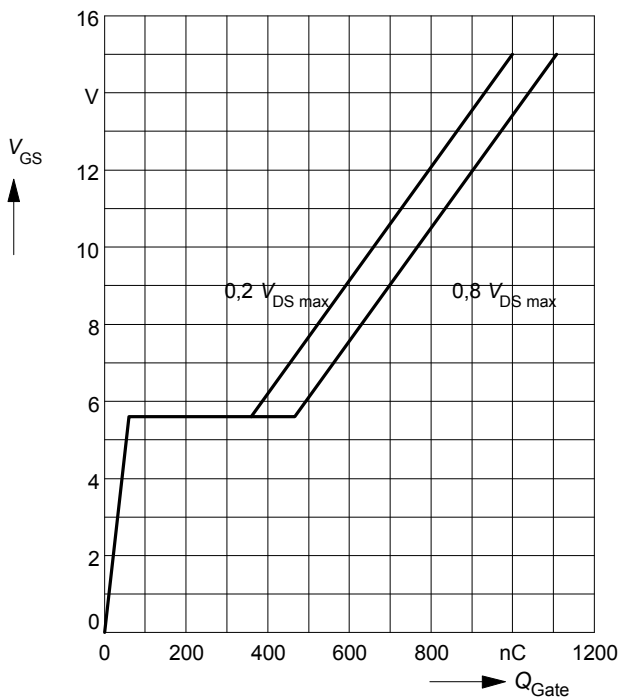
$$V_{(BR)DSS} = f(T_j)$$



Typ. gate charge

$$V_{GS} = f(Q_{Gate})$$

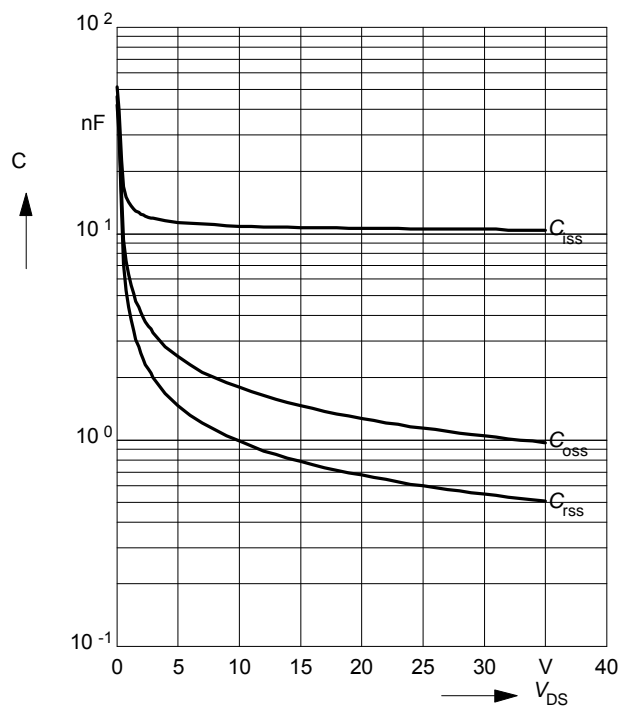
parameter: $I_{D\text{ puls}} = 53\text{ A}$



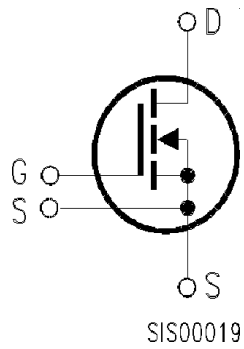
Typ. capacitances

$$C = f(V_{DS})$$

parameter: $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$



Circuit Diagramm



Package Outlines

Dimension in mm

Weight: 130 g

